

# MBRM1H100T3G

## Surface Mount Schottky Power Rectifier

### POWERMITE<sup>®</sup> Power Surface Mount Package

The Schottky Powermite<sup>®</sup> employs the Schottky Barrier principle with a barrier metal and epitaxial construction that produces optimal forward voltage drop–reverse current tradeoff. The advanced packaging techniques provide for a highly efficient micro miniature, space saving surface mount Rectifier. With its unique heatsink design, the Powermite<sup>®</sup> has the same thermal performance as the SMA while being 50% smaller in footprint area. Because of its small size, it is ideal for use in portable and battery powered products such as cellular and cordless phones, chargers, notebook computers, printers, PDAs and PCMCIA cards. Typical applications are AC–DC and DC–DC converters, reverse battery protection, and “ORing” of multiple supply voltages and any other application where performance and size are critical.

#### Features

- Low Profile – Maximum Height of 1.1 mm
- Small Footprint – Footprint Area of 8.45 mm<sup>2</sup>
- Low  $V_F$  Provides Higher Efficiency and Extends Battery Life
- Supplied in 12 mm Tape and Reel
- Low Thermal Resistance with Direct Thermal Path of Die on Exposed Cathode Heat Sink
- This is a Pb–Free Device

#### Mechanical Characteristics:

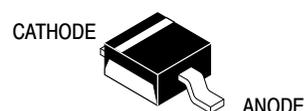
- Powermite<sup>®</sup> is JEDEC Registered as D0–216AA
- Case: Molded Epoxy
- Epoxy Meets UL 94 V–0 @ 0.125 in
- Weight: 16.3 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds



ON Semiconductor<sup>®</sup>

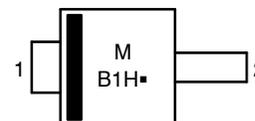
<http://onsemi.com>

### SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES, 100 VOLTS



POWERMITE  
CASE 457  
PLASTIC

#### MARKING DIAGRAM



M = Date Code  
B1H = Device Code  
▪ = Pb–Free Package

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MBRM1H100T3G	Powermite (Pb–Free)	12000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MBRM1H100T3G

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	100	V
Average Rectified Forward Current ( $T_L = 168^\circ\text{C}$ )	$I_O$	1.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	50	A
Storage and Operating Junction Temperature Range (Note 1)	$T_{stg}, T_J$	-65 to +175	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2)	$\Psi_{JCL}$	12	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	75	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{\theta JA}$	260	$^\circ\text{C}/\text{W}$

## ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 4) ( $I_F = 1.0 \text{ A}, T_J = 25^\circ\text{C}$ ) ( $I_F = 2.0 \text{ A}, T_J = 25^\circ\text{C}$ ) ( $I_F = 1.0 \text{ A}, T_J = 125^\circ\text{C}$ ) ( $I_F = 2.0 \text{ A}, T_J = 125^\circ\text{C}$ )	$V_F$	0.76 0.84 0.61 0.68	V
Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, $T_J = 25^\circ\text{C}$ ) (Rated dc Voltage, $T_J = 125^\circ\text{C}$ )	$I_R$	20 1.0	$\mu\text{A}$ mA

- Mounted with 700 mm<sup>2</sup> copper pad size (Approximately 1 in<sup>2</sup>) 1 oz FR4 Board.
- Mounted with pad size approximately 20 mm<sup>2</sup> copper, 1 oz FR4 Board.
- Pulse Test: Pulse Width  $\leq 380 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

# MBRM1H100T3G

## TYPICAL CHARACTERISTICS

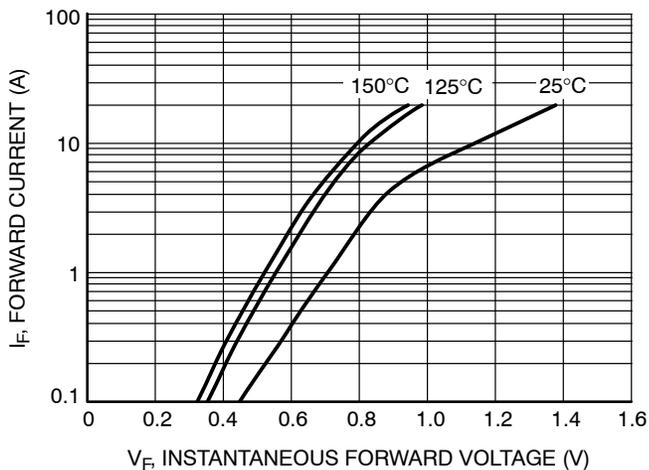


Figure 1. Typical Forward Voltage

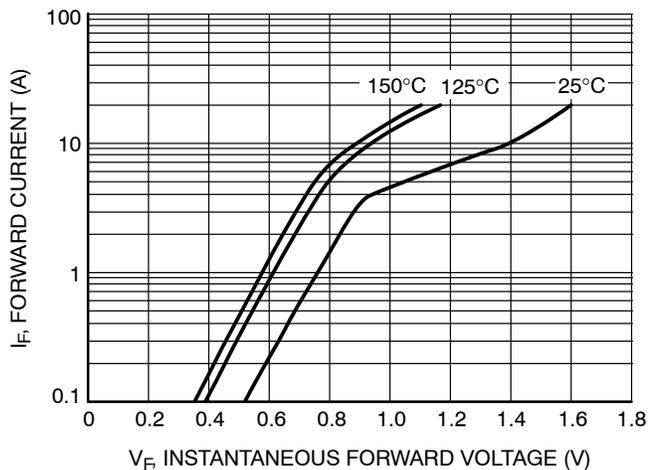


Figure 2. Maximum Forward Voltage

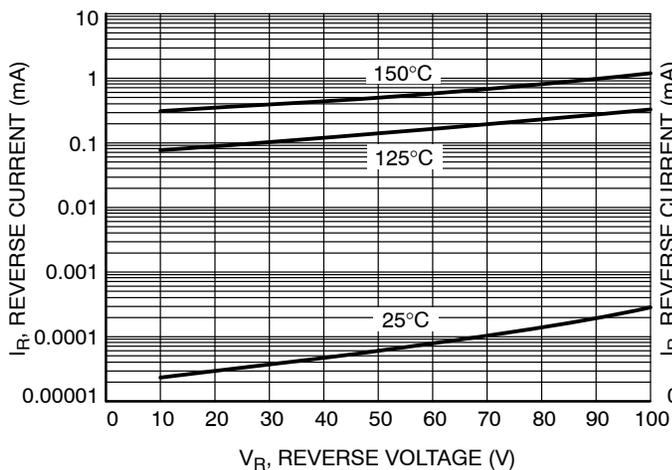


Figure 3. Typical Reverse Current

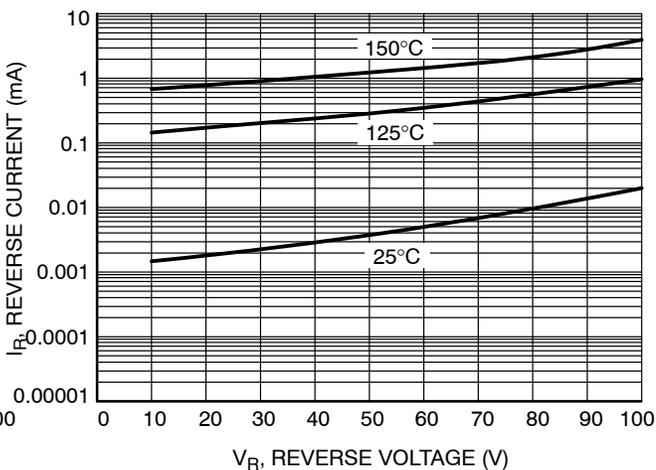


Figure 4. Maximum Reverse Current

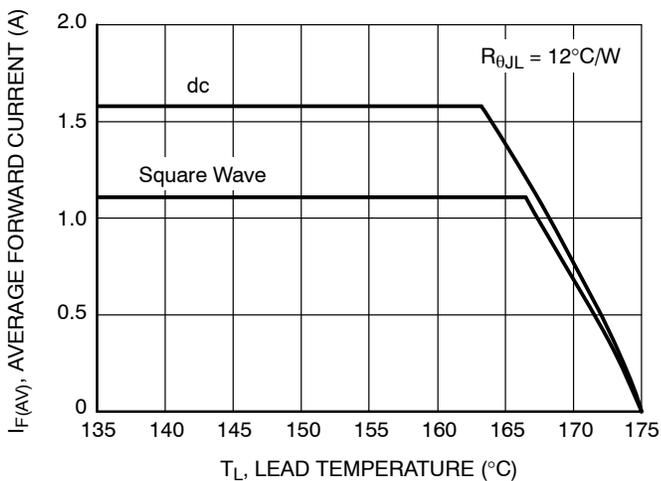


Figure 5. Current Derating

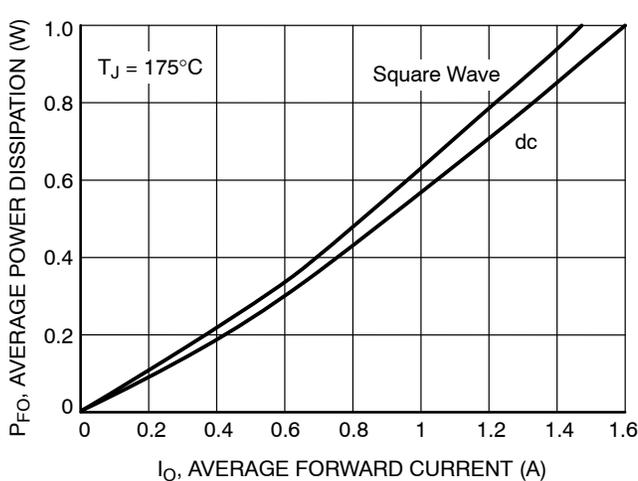


Figure 6. Forward Power Dissipation

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## TYPICAL CHARACTERISTICS

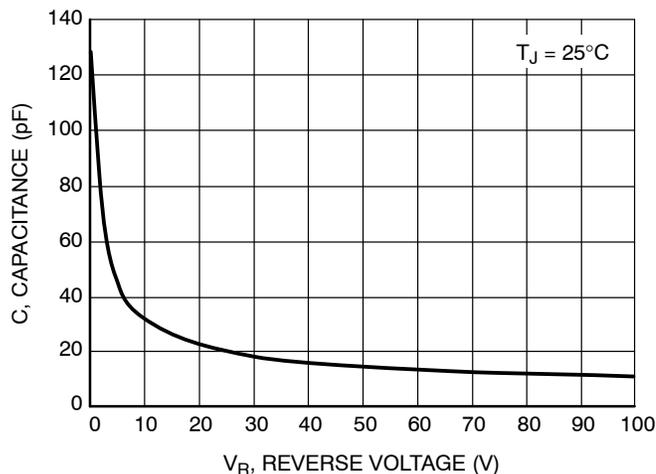


Figure 7. Capacitance

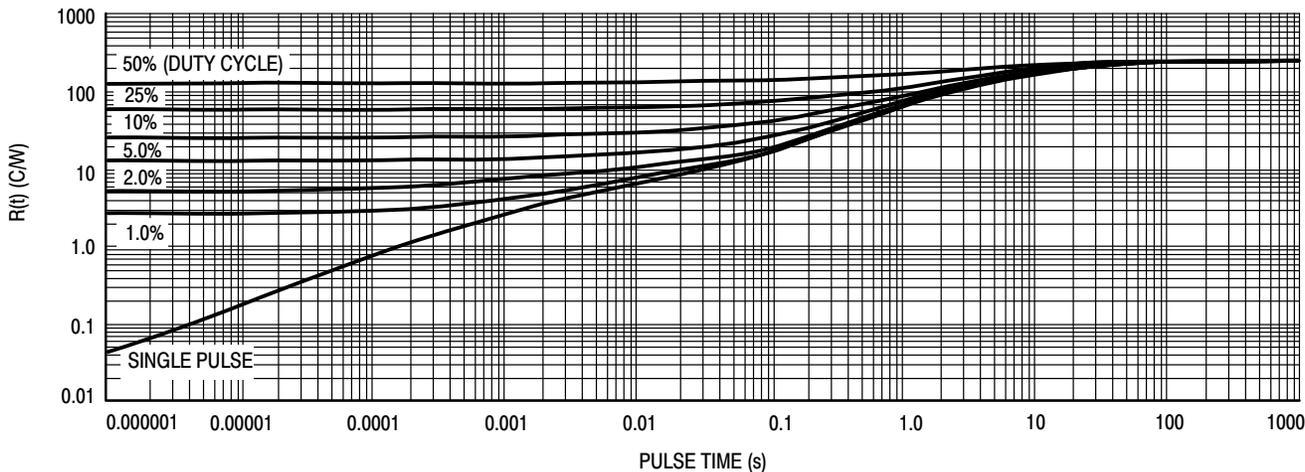


Figure 8. Thermal Response, Junction-to-Ambient (20 mm<sup>2</sup> pad)

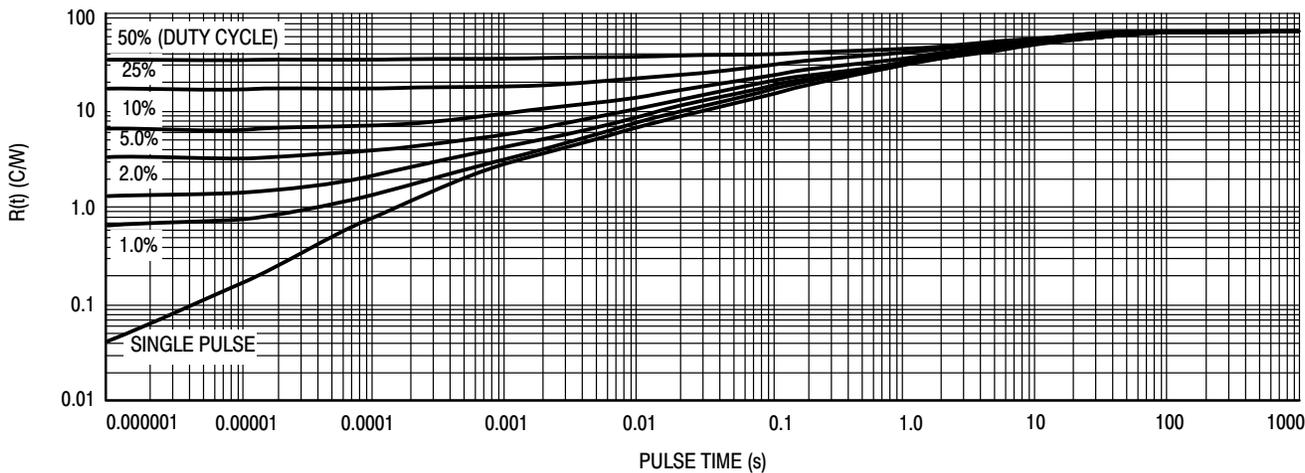
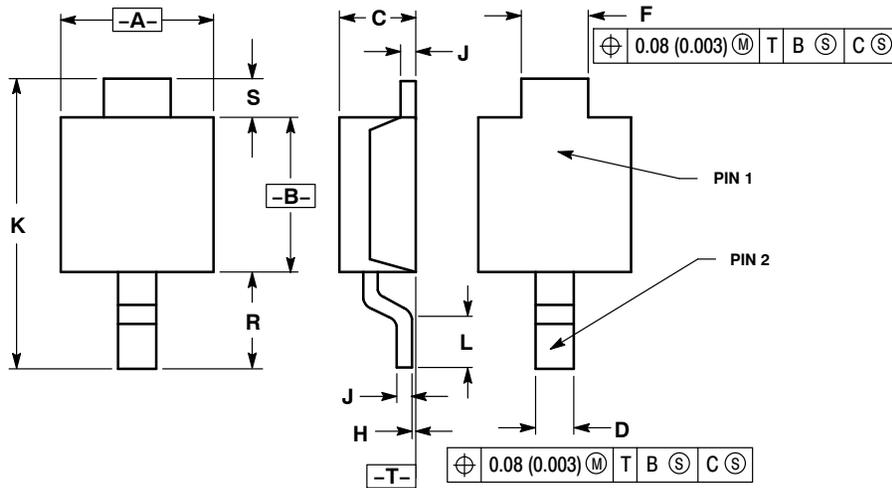


Figure 9. Thermal Response, Junction-to-Ambient (1 in<sup>2</sup> pad)

# MBRM1H100T3G

## PACKAGE DIMENSIONS

POWERMITE  
CASE 457-04  
ISSUE E

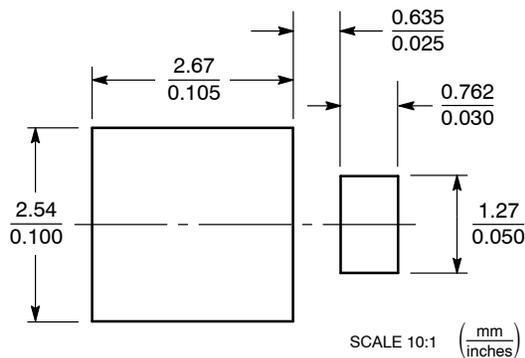


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.75	2.05	0.069	0.081
B	1.75	2.18	0.069	0.086
C	0.85	1.15	0.033	0.045
D	0.40	0.69	0.016	0.027
F	0.70	1.00	0.028	0.039
H	-0.05	+0.10	-0.002	+0.004
J	0.10	0.25	0.004	0.010
K	3.60	3.90	0.142	0.154
L	0.50	0.80	0.020	0.031
R	1.20	1.50	0.047	0.059
S	0.50	REF	0.019	REF

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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